CIRCUITS LLC
Quality Across the Board

# PCB Capabilities

| *Via Structure* | Standard High Yield | Advanced Reduced Yield | Engineering Low Yield | Notes |
|---|---|---|---|---|
| Mechanical Blind Vias | ✓ | ✓ | ✓ | |
| Mechanical Buried Vias | ✓ | ✓ | ✓ | |
| Laser Drilled Microvias | ✓ | ✓ | ✓ | |
| Stacked Microvias | --- | --- | ✓ | |
| Back Drilling | ✓ | ✓ | ✓ | |
| Non Conductive Via Fill | ✓ | ✓ | ✓ | |
| Conductive Via Fill | --- | ✓ | ✓ | |
| *Surface Finishes* | | | | |
| Electroless Nickel Immersion Gold (ENIG) | ✓ | ✓ | ✓ | |
| Hot Air Solder Leveling (HASL) | ✓ | ✓ | ✓ | |
| ENEPIG | --- | ✓ | ✓ | |
| Soft Wirebondable Gold | --- | ✓ | ✓ | Requires Selective Plating |
| Hard Electroplated Gold for Contacts | --- | ✓ | ✓ | Requires Selective Plating |
| Immersion Silver (IAg) | ✓ | ✓ | ✓ | Handling and Shelf Life Concerns |
| Organic Surface Protection (OSP) | --- | ✓ | ✓ | Handling and Shelf Life Concerns |



The information contained in this document is intended for reference only and may not be applicable to all designs.